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United States Patent [19]

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Nakao et al.

[45] Date of Patent: **** Jun. 16, 1992**

[54] **INSTRUMENT FOR TRANSFERRING BOATS FOR THERMAL TREATMENT OF SEMICONDUCTOR WAFERS**

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[**] Term: **14 Years**

[57] CLAIM

[21] Appl. No.: **301,994**

The ornamental design for an instrument for transferring boats for thermal treatment of semiconductor wafers, as shown.

[22] Filed: **Jan. 25, 1989**

[30] Foreign Application Priority Data

Jul. 25, 1988 [JP] Japan 63-29835

DESCRIPTION

[52] U.S. Cl. **D15/144**

[58] Field of Search D15/144, 199; 219/390, 219/411; 414/222, 225, 226, 483; 432/6, 153, 239, 253, 258-261

FIG. 1 is a front elevational view of an instrument for transferring boats for thermal treatment of semiconductor wafers showing our new design;

FIG. 2 is an elevational view, the remainder of the cylindrical member being the same throughout in appearance;

FIG. 3 is a top plan view;

FIG. 4 is a bottom plan view;

FIG. 5 is an elevational view thereof;

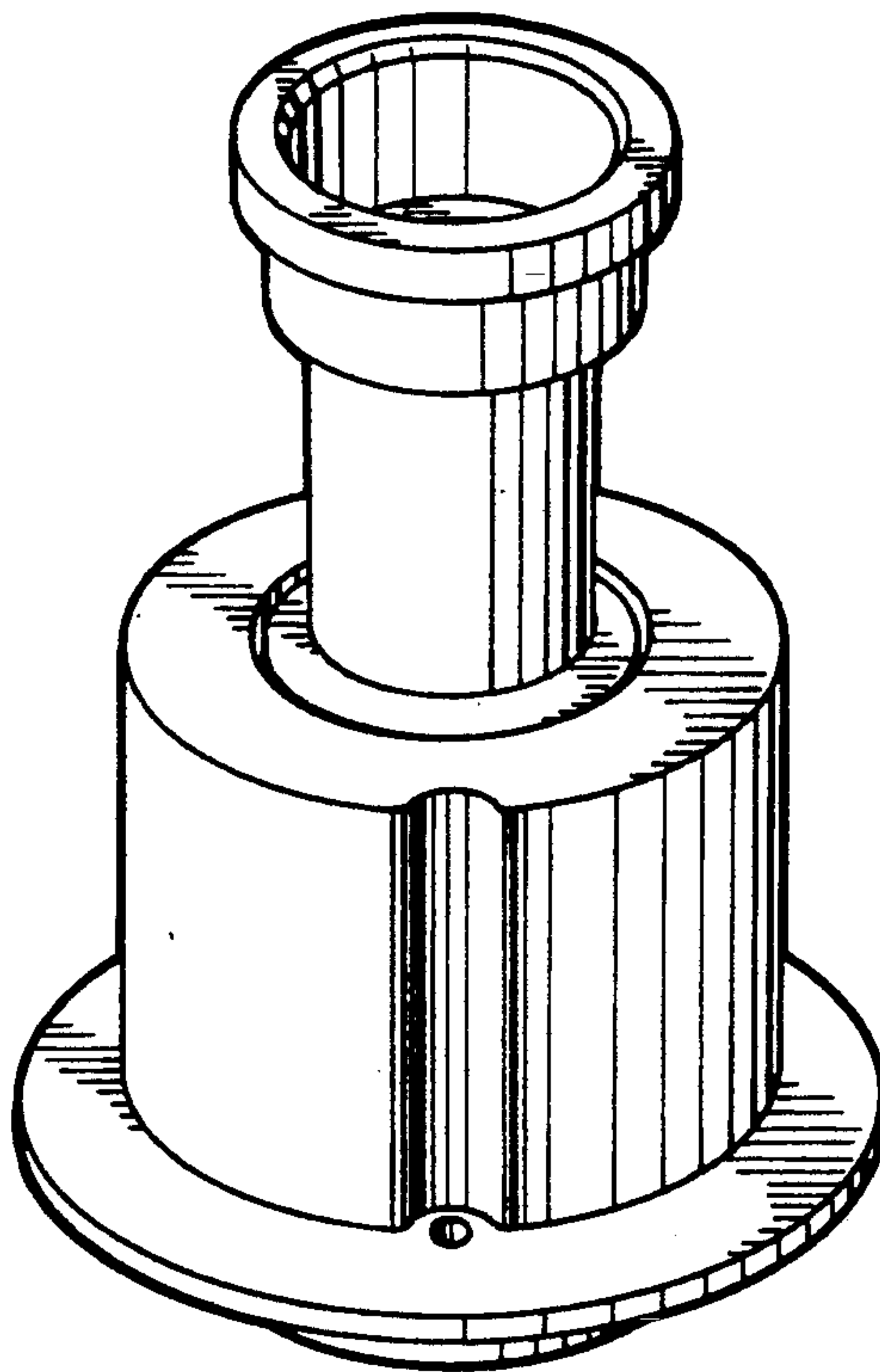
FIG. 6 is a top perspective view; and,

FIG. 7 is a bottom perspective view thereof.

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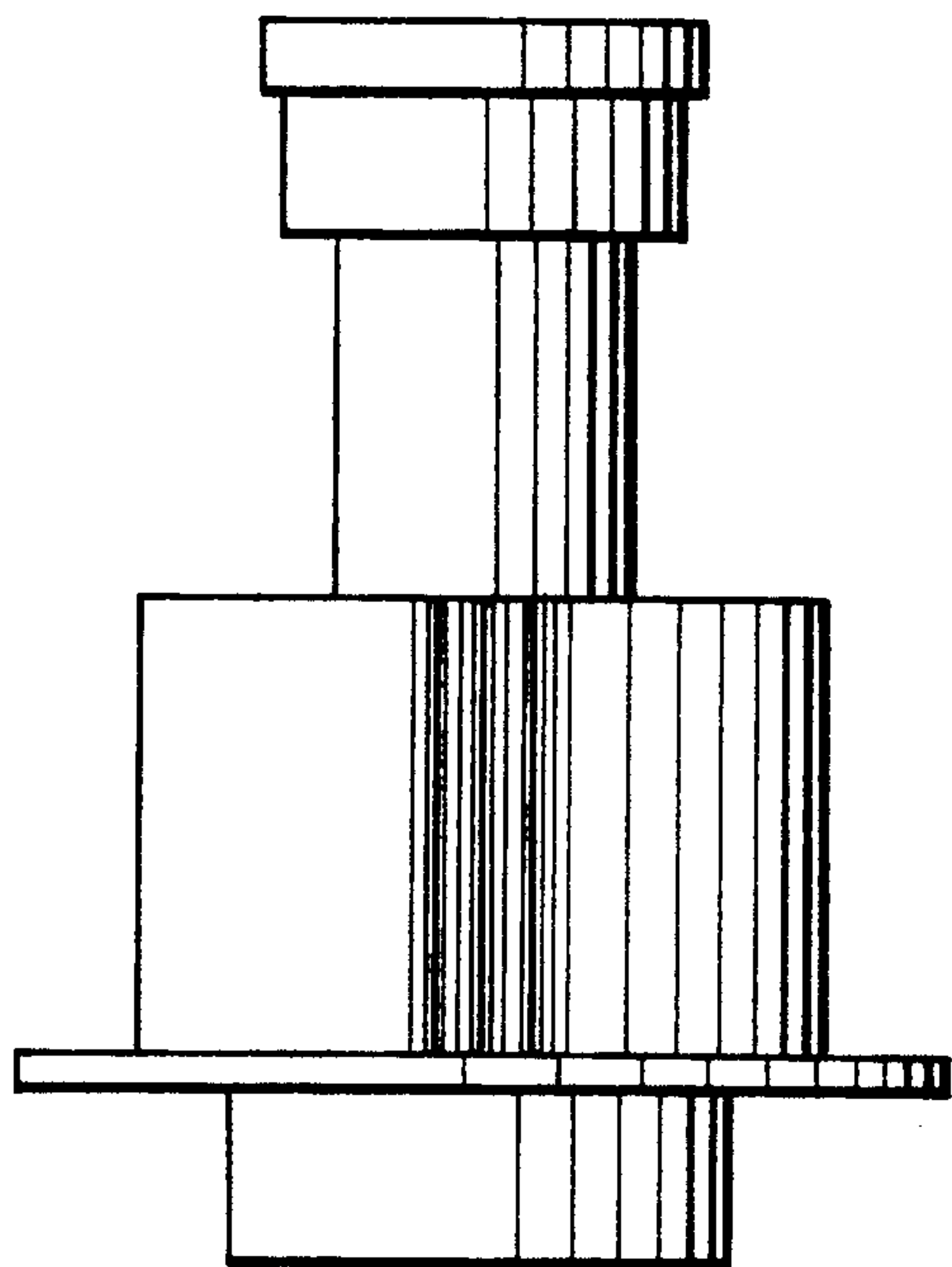


FIG. 1

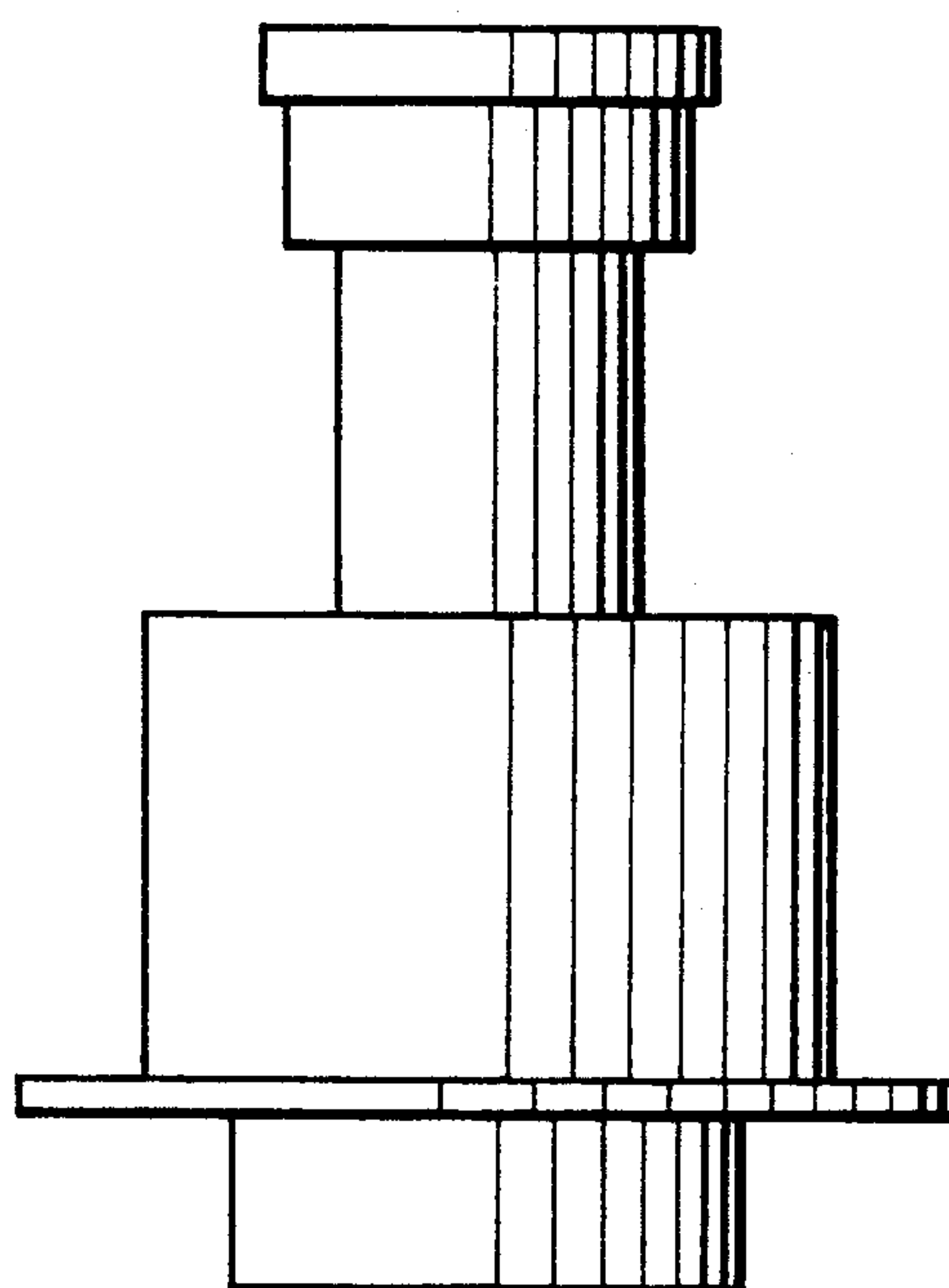


FIG. 2

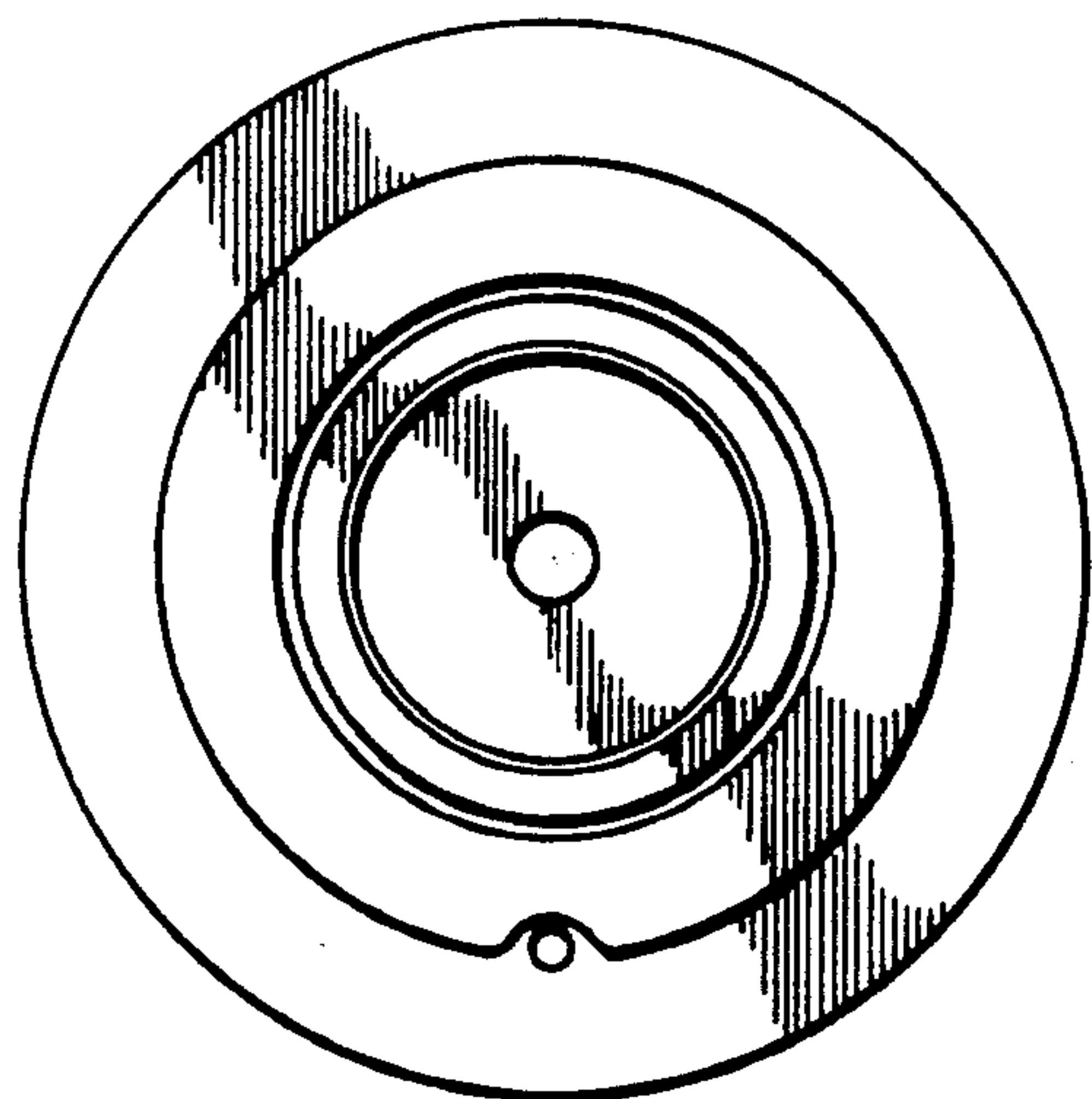


FIG. 3

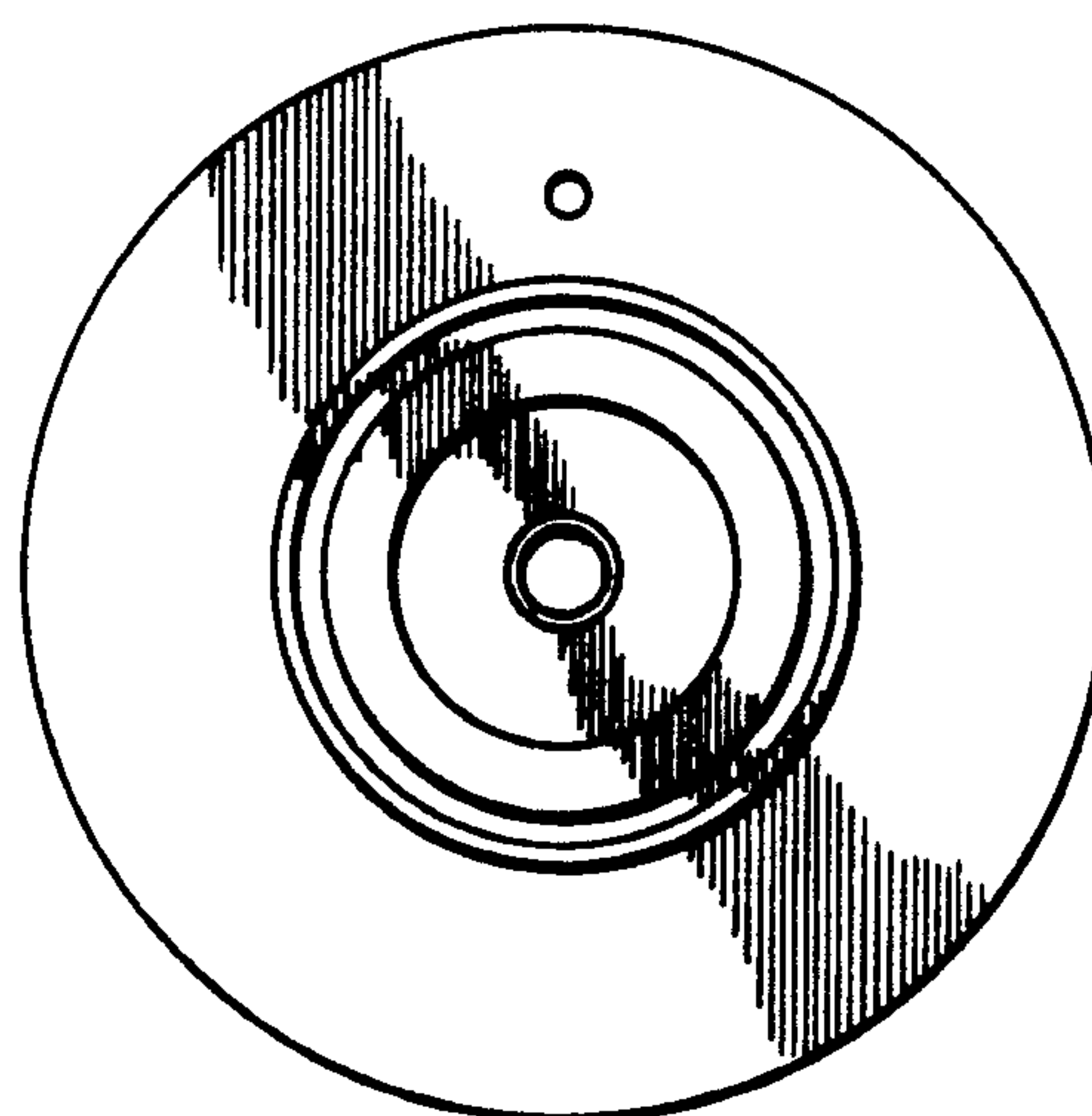


FIG. 4

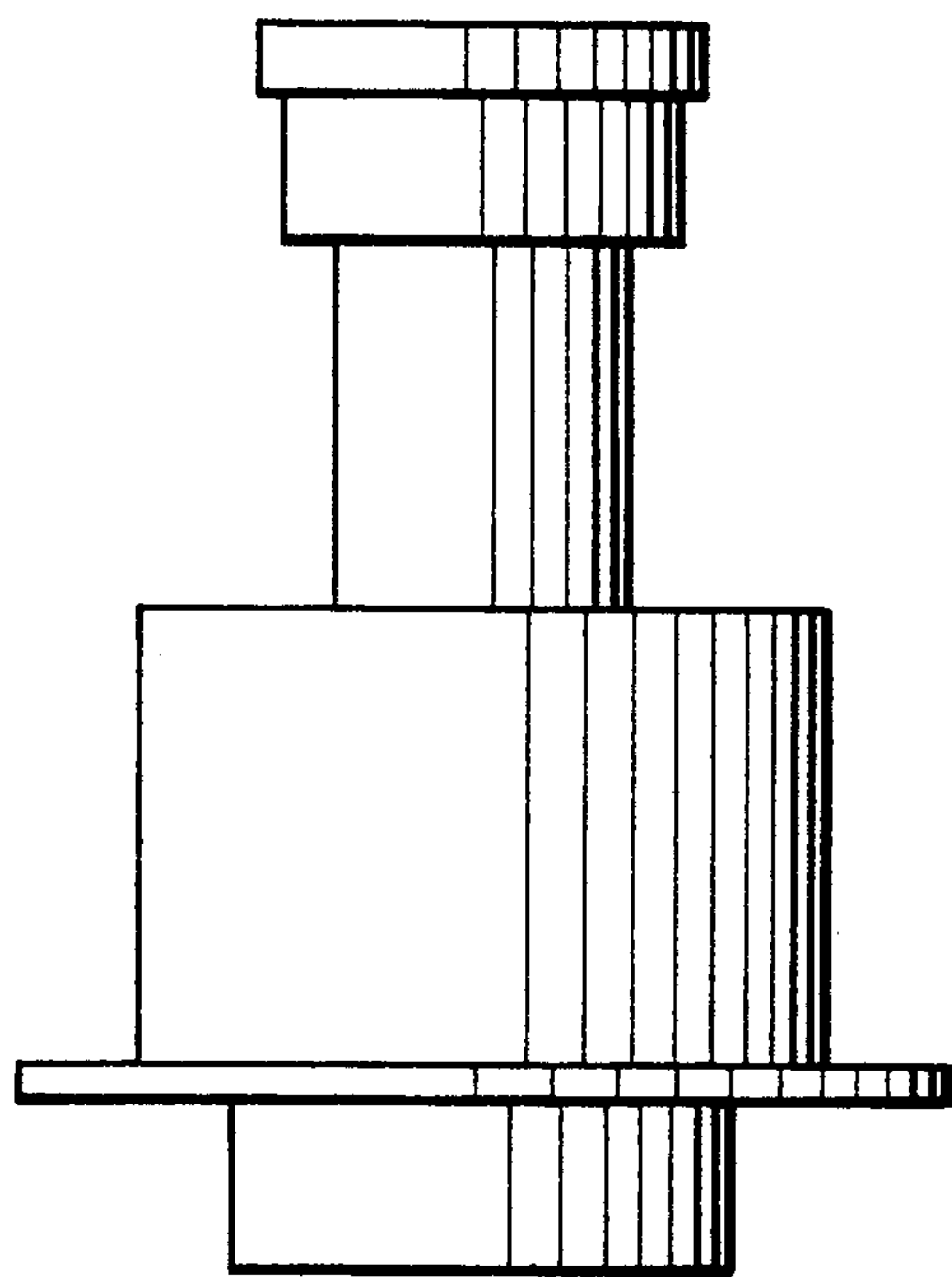


FIG. 5

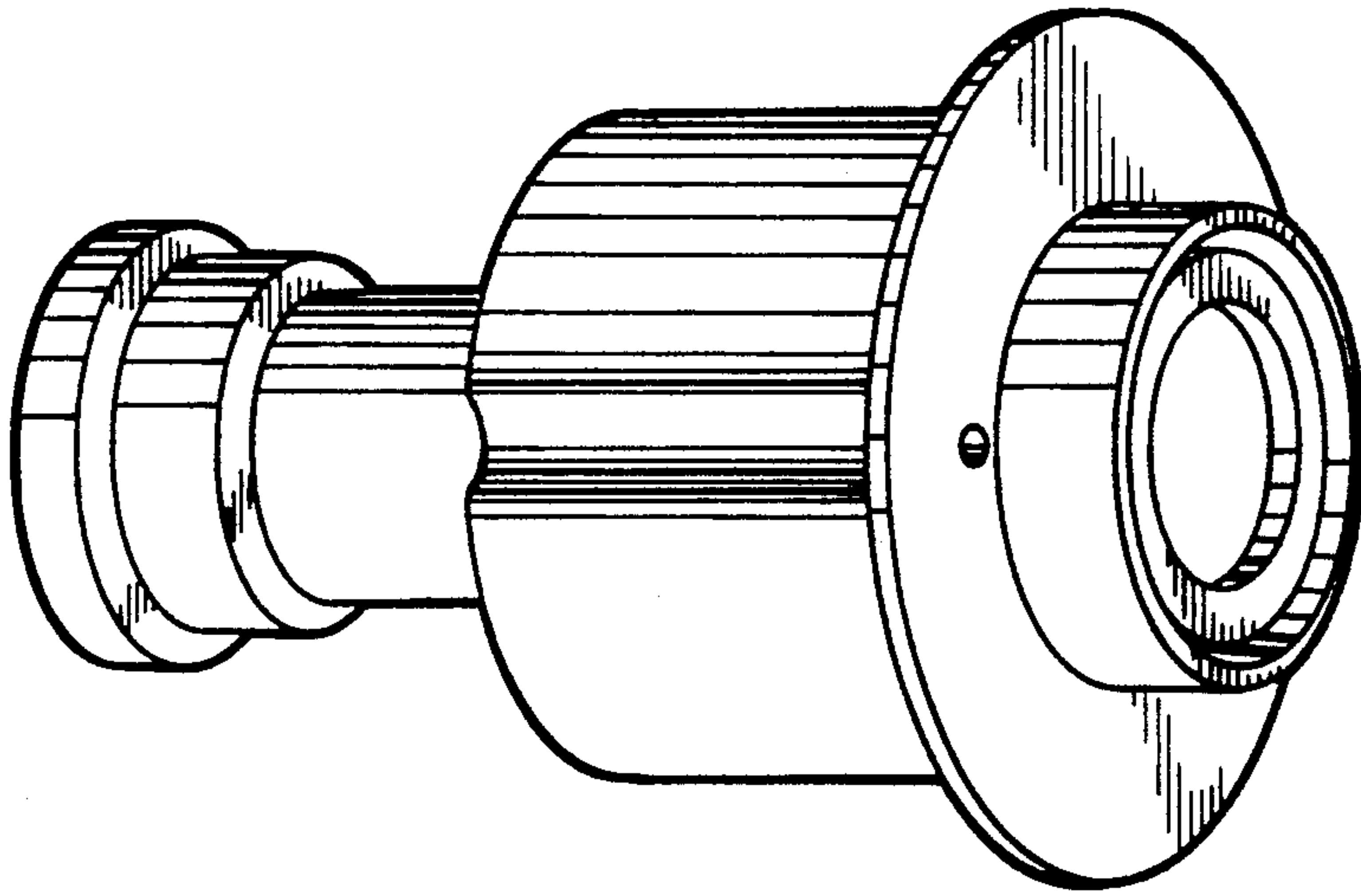


FIG. 7

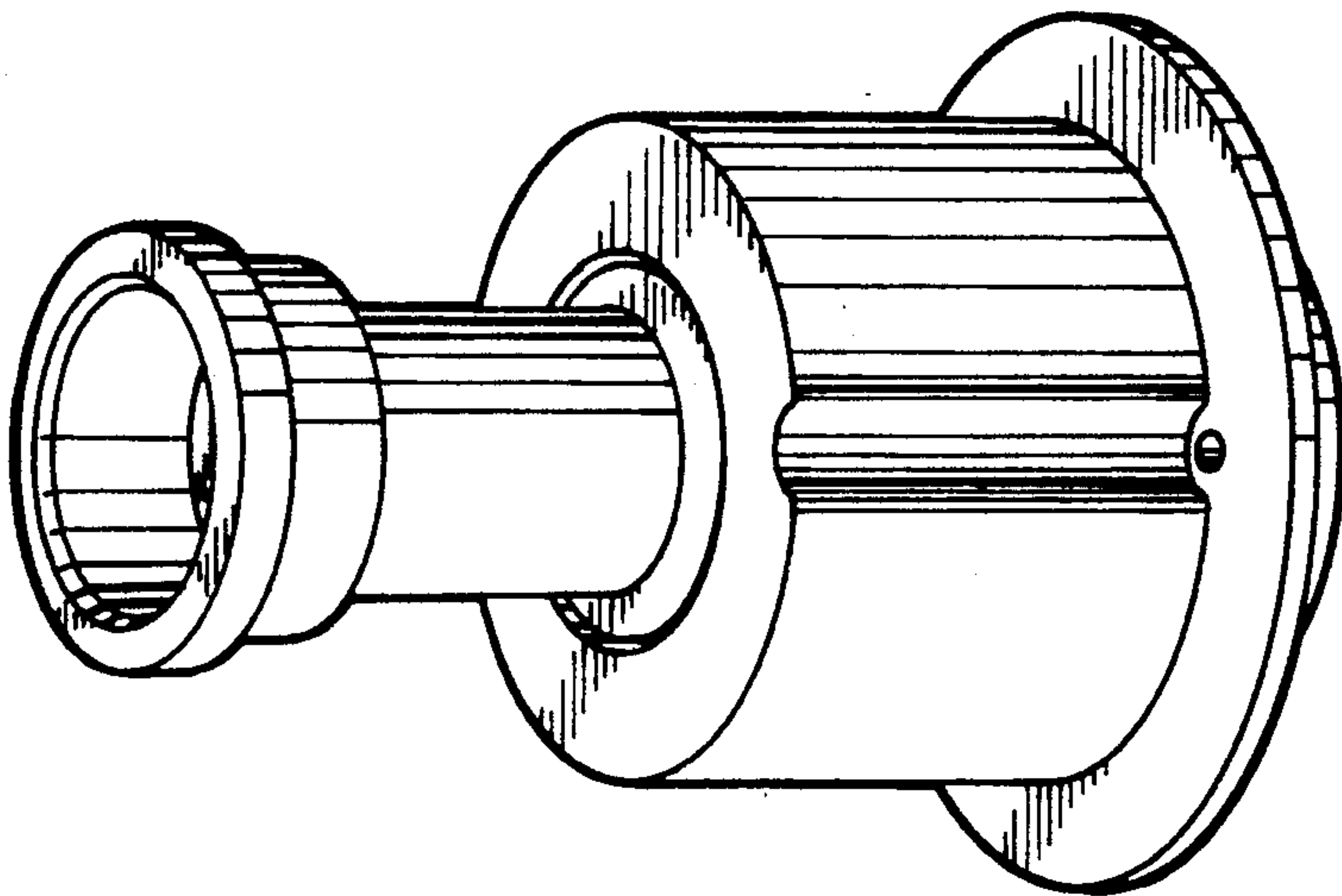


FIG. 6